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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	32
Number of Macrocells	1024
Number of Gates	-
Number of I/O	384
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	676-BBGA
Supplier Device Package	676-FPBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc51024vg-5f676c

The ispMACH5000VG devices also contain sysCLOCK Phase Locked Loops (PLLs) that provide designers with increased clocking flexibility. The PLLs can be used to synthesize new clocks for use on-chip or elsewhere within the system. They can also be used to deskew clocks, again both at the chip and system levels. A variable delay line capability further improves this and allows designers to retard or advance the clock in order to tune set-up and clock-to-out times for optimal results. The ispMACH 5000VG Family Selection Guide (Table 1) details the key attributes and packages for the ispMACH 5000VG devices.

ispMACH 5000VG Architecture

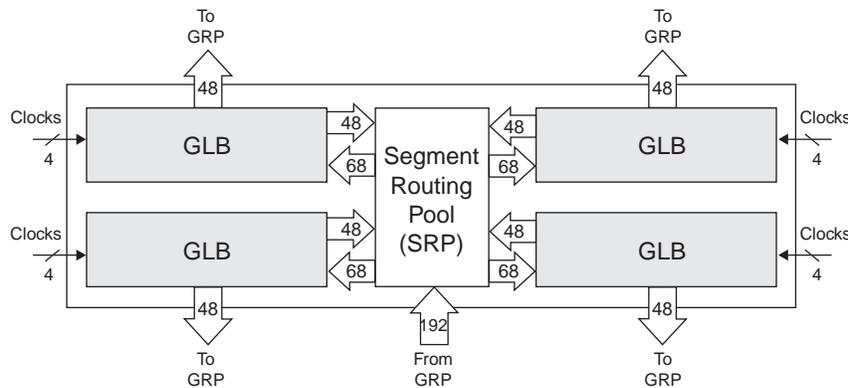
The ispMACH 5000VG Family of In-System Programmable High Density Logic Devices is based on segments containing four Generic Logic Blocks (GLBs) and a hierarchical routing pool (GRP) structure interconnecting the segments. A segment routing pool (SRP) connects each GLB in a segment allowing the maximum flexibility and speed.

Outputs from the GLBs drive the Segment Routing Pool (SRP) and the Global Routing Pool (GRP). Enhanced switching resources are provided to allow signals in the Segment Routing Pool to drive any or all the GLBs in the segment. Optimal switching is provided to allow all signals in the Global Routing Pool to be routed to any or all SRPs. This mechanism allows fast, efficient connections across the entire device.

Segment

Each segment contains four GLBs and a segment routing pool (SRP). Each GLB has 32 internal feedback outputs and 16 external feedback outputs, for a total of 48 outputs from each GLB feeding the SRP. The SRP contains up to 384 signals, 48 from each GLB and 192 from the GRP, with full routing capability. This routing scheme maximizes the flexibility and speed of the device without sacrificing the routing.

Figure 2. Segment



Generic Logic Block

Each GLB contains 32 macrocells and a fully populated, programmable AND-array with 160 logic product terms and three control product terms. The GLB has 68 inputs from the Segment Routing Pool, which are available in both true and complement form for every product term. The three control product terms are used for shared reset, clock and output enable functions. Figure 3 shows the structure of the GLB from the macrocell perspective. This is referred to as a macrocell slice. There are 32 macrocell slices per GLB.

AND-Array

The programmable AND-Array consists of 68 inputs and 163 output product terms. The 68 inputs from the SRP are used to form 136 lines in the AND-Array (true and complement of the inputs). Each line in the array can be connected to any of the 163 output product terms via a wired AND. Each of the 160 logic product terms feed the Dual-OR Array with the remaining three control product terms feeding the Shared PT Clock, Shared PT Reset and Shared PT OE. Every set of five product terms from the 160 logic product terms forms a product term cluster start-

Figure 3. Macrocell Slice

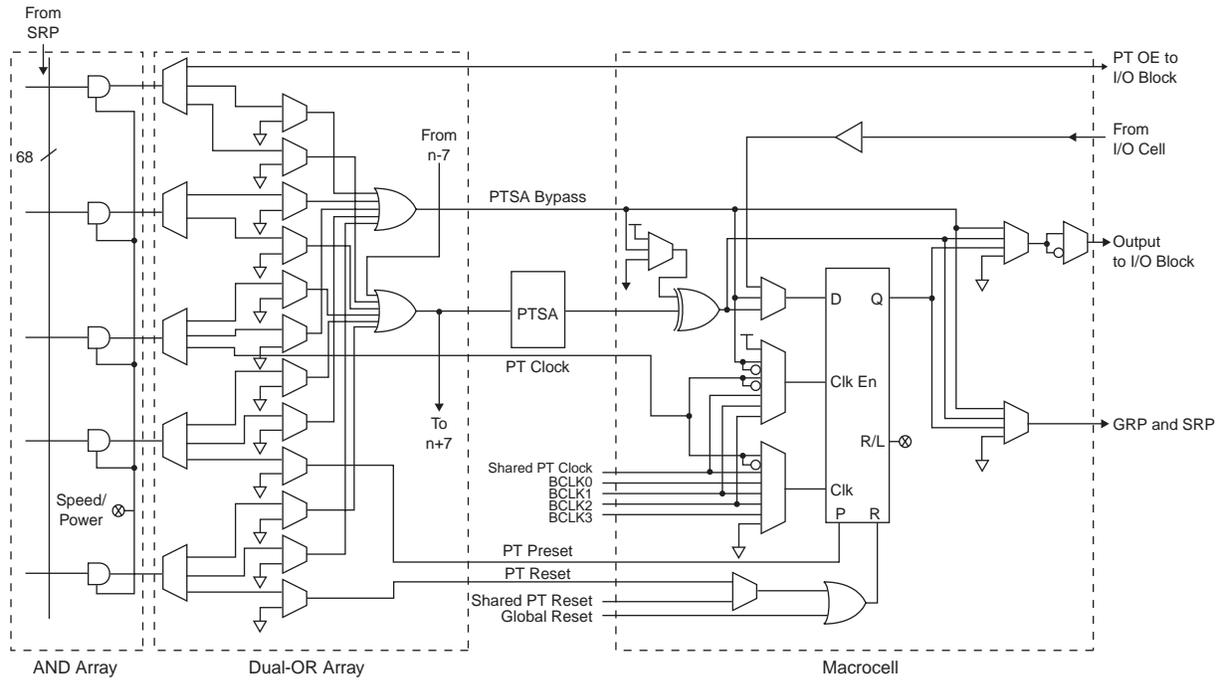
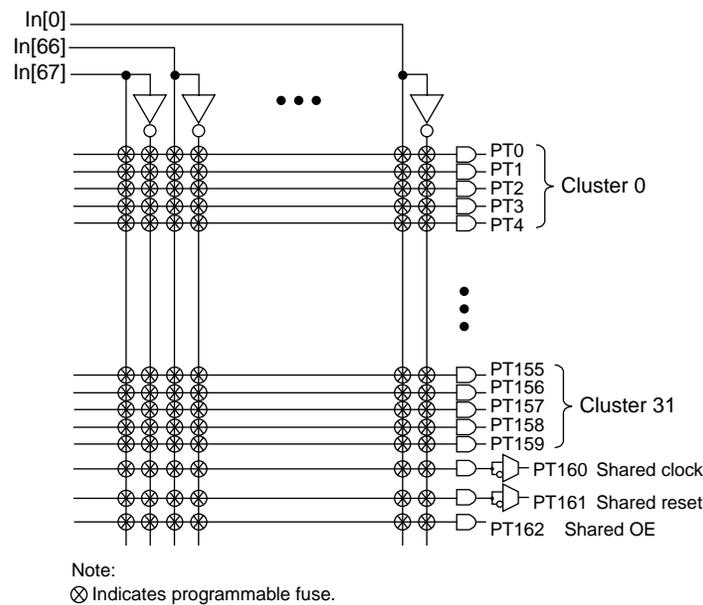
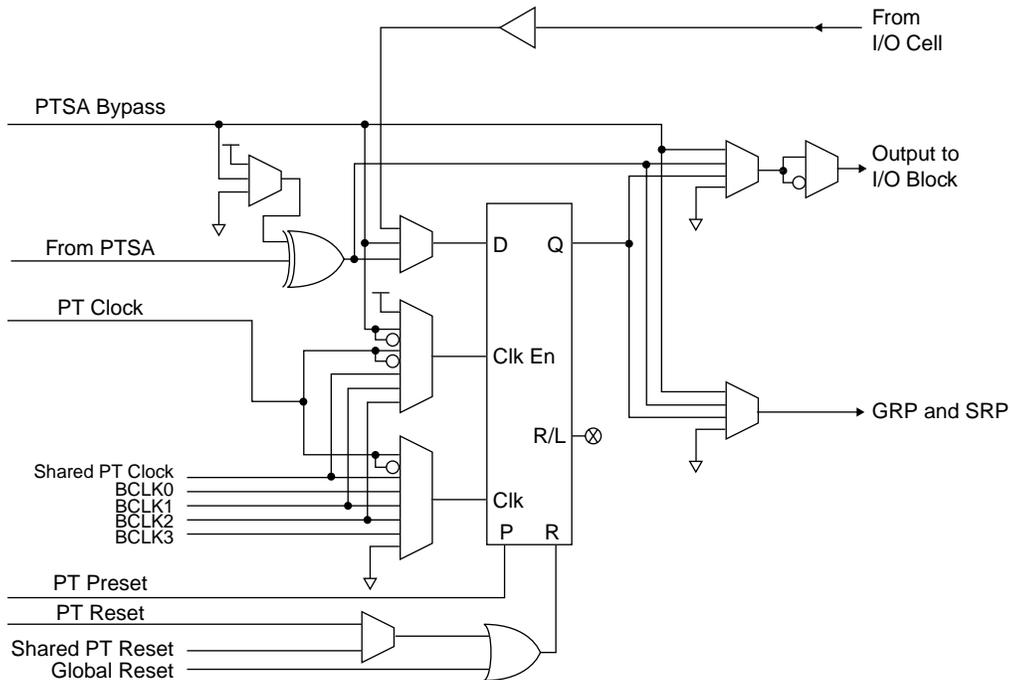


Figure 4. AND-Array



ing with PT0. There is one product term cluster for every macrocell in the GLB. In addition to the three control product terms, the first, third, fourth and fifth product terms of each cluster can be used as a PTOE (output macrocells only), PT Clock, PT Preset and PT Reset, respectively. Figure 4 is a graphical representation of the AND-Array.

Figure 7. Macrocell



I/O Cell

The I/O cell of the ispMACH 5000VG device provides a high degree of flexibility. It includes the sysIO feature and an enhanced output enable MUX for optimal performance both on- and off-chip. The sysIO feature allows I/O cells to be configured to different I/O standards, drive strengths and slew rates. The enhanced output enable MUX provides up to 14 different output enable choices per I/O cell.

The I/O cell contains an output enable (OE) MUX, a programmable tri-state output buffer, a programmable input buffer, a programmable pull-up resistor, a programmable pull-down resistor and a programmable bus-keeper latch. The I/O cell receives its input from its associated macrocell. The I/O cell has a feedback line to its associated macrocell and a direct path to the GRP and SRP.

The output enable (OE) MUX selects the OE signal per I/O cell. The inputs to the OE MUX are the four Shared PTOE signals, PTOE and the two GOE signals. The OE MUX also has the ability to choose either the true or inverse of each of these signals. The output of the OE MUX goes through a logical AND with the TOE signal to allow easy tri-stating of the outputs for testing purposes.

The four shared PTOE signals are derived from PT163 of each GLB in the segment. The PTOE signal is derived from the first product term in each macrocell cluster, which is directly routed to the OE MUX. Therefore, every I/O cell can have a different OE signal. Figure 8 is a graphical representation of the I/O cell.

sysIO Recommended Operating Conditions²

Standard	V _{CCO} (V)		V _{REF} (V)	
	Min	Max	Min	Max
LVC MOS 3.3 ¹	3.0	3.6	—	—
LVC MOS 2.5	2.3	2.7	—	—
LVC MOS 1.8	1.65	1.95	—	—
LV TTL	3.0	3.6	—	—
PCI 3.3	3.0	3.6	—	—
PCI-X	3.0	3.6	—	—
AGP-1X	3.15	3.45	—	—
SSTL 2	2.3	2.7	1.15	1.35
SSTL 3	3.0	3.6	1.3	1.7
CTT 3.3	3.0	3.6	1.35	1.65
CTT 2.5	2.3	2.7	1.35	1.65
HSTL	1.4	1.6	0.68	0.9
GTL+	1.4	3.6	0.882	1.122

1. Software default setting.

2. Typical values for V_{CCO} and V_{REF} are the average of the Min and Max values.

ispMACH 51024VG External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description ^{1,2,3}	-5		-75		-10		-12		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD}	Data propagation delay, 5-PT bypass	—	5.0	—	7.5	—	10.0	—	12.0	ns
t _{PD_PTSA}	Data propagation delay, intrasegment path	—	6.0	—	9.0	—	11.5	—	13.5	ns
t _{PD_GLOBAL}	Data propagation delay, intersegment path	—	6.5	—	9.75	—	13.0	—	16.0	ns
t _S	GLB register setup time before clock, 5-PT bypass	3.0	—	5.0	—	7.5	—	9.3	—	ns
t _{S_PTSA}	GLB register setup time before clock	3.0	—	6.0	—	8.5	—	10.0	—	ns
t _{SIR}	GLB register setup time before clock, input register path	2.8	—	3.0	—	4.0	—	5.0	—	ns
t _H	GLB register hold time before clock, 5-PT bypass	0.0	—	0.0	—	0.0	—	0.0	—	ns
t _{H_PTSA}	GLB register hold time before clock	0.0	—	0.0	—	0.0	—	0.0	—	ns
t _{HIR}	GLB register hold time before clock, input reg. path	0.0	—	0.0	—	0.0	—	0.0	—	ns
t _{CO}	GLB register clock-to-output delay	—	4.4	—	5.0	—	6.0	—	7.0	ns
t _R	External reset pin to output delay	—	6.5	—	9.0	—	10.0	—	10.9	ns
t _{RW}	External reset pulse duration	4.0	—	6.0	—	8.0	—	9.5	—	ns
t _{LPTOE/DIS}	Input to output local product term output enable/disable	—	7.0	—	9.75	—	11.5	—	13.4	ns
t _{SPTOE/DIS}	Input to output segment product term output enable/disable	—	8.0	—	11.25	—	17.5	—	20.4	ns
t _{GOE/DIS}	Global OE input to output enable/disable	—	6.2	—	7.5	—	8.85	—	10.0	ns
t _{CW}	Global clock width, high or low	1.6	—	2.75	—	3.6	—	4.3	—	ns
t _{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.8	—	2.75	—	3.6	—	4.3	—	ns
t _{WIR}	Input register clock width, high or low	1.8	—	2.75	—	3.6	—	4.3	—	ns
t _{SKEW}	Clock-to-out skew, block level	—	0.25	—	0.35	—	0.45	—	0.55	ns
	Clock-to-out skew, segment level	—	0.4	—	0.5	—	0.6	—	0.7	ns
f _{MAX} ⁴	Clock frequency with internal feedback	178.6	—	117.0	—	87.0	—	73.0	—	MHz
f _{MAX} (Ext.)	Clock frequency with external feedback, 1/(t _{S_PTSA} + t _{CO})	135.1	—	90.9	—	69.0	—	58.8	—	MHz
f _{MAX} (Tog.)	Clock frequency max Toggle	312.5	—	181.0	—	138.0	—	116.0	—	MHz

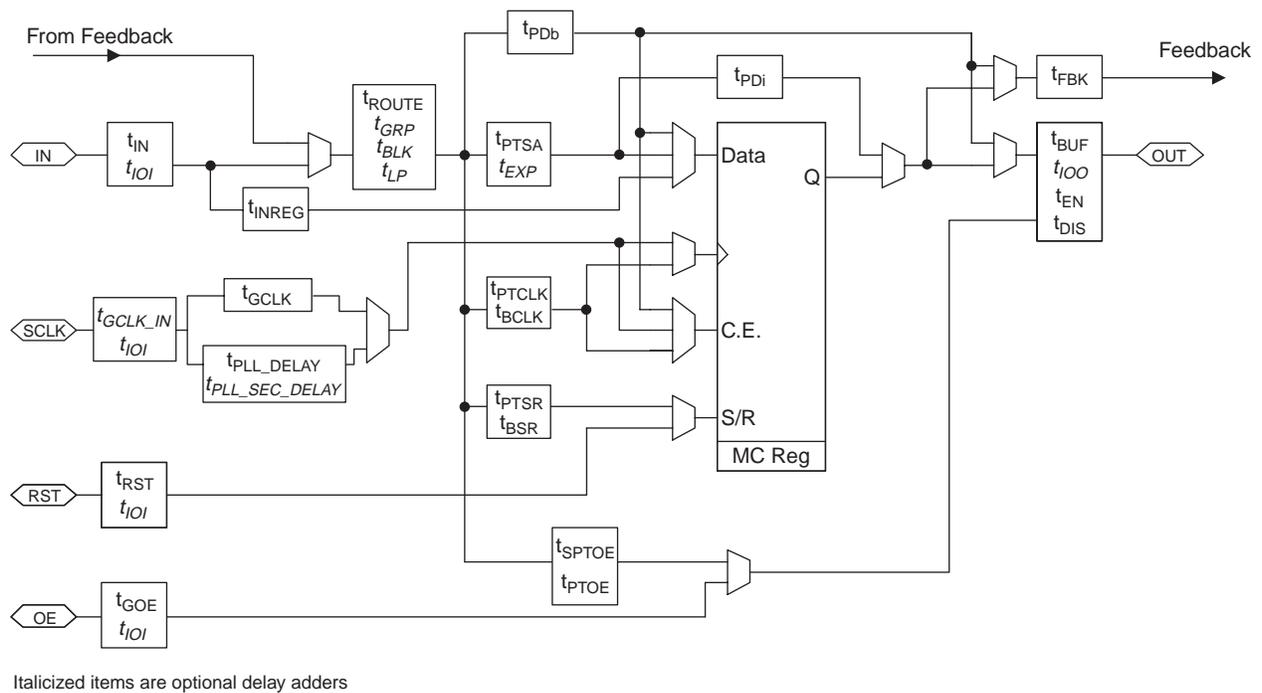
Timing v.1.10

1. Timing numbers are based on default LVCMOS 3.3 I/O Buffers. Use timing adjusters provided to calculate timing for other standards.
2. Measured using standard switching circuit, assuming segment and global routing loading of 1, worst case PTSA loading and 1 output switching.
3. Pulse widths and clock widths less than minimum will cause unknown behavior.
4. Standard 16-bit counter using SRP feedback.

Timing Model

The task of determining the timing through the ispMACH 5000VG family, like any CPLD, is relatively simple. The timing model provided in Figure 11 shows the specific delay paths. Once the implementation of a given function is determined either conceptually or from the software report file, the delay path of the function can easily be determined from the timing model. The Lattice design tools report the timing delays based on the same timing model for a particular design. Note that the internal timing parameters are given for reference only, and are not tested. The external timing parameters are tested and guaranteed for every device. For more information on the timing model and usage, please refer to Technical Note TN1001: *ispMACH 5000VG Timing Model Design and Usage Guidelines*.

Figure 11. ispMACH 5000VG Timing Model



ispMACH 5768VG Internal Timing Parameters

Over Recommended Operating Conditions

Parameter	Description	-5		-75		-10		-12		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
In/Out Delays										
t_{IN}	Input Buffer Delay	—	0.65	—	0.95	—	1.25	—	1.40	ns
t_{GCLK_IN}	Global Clock Input Buffer Delay	—	0.65	—	0.95	—	1.25	—	1.40	ns
t_{GOE}	Global OE Pin Delay	—	4.05	—	5.00	—	6.00	—	7.00	ns
t_{BUF}	Delay through Output Buffer	—	1.15	—	1.50	—	1.75	—	1.90	ns
t_{EN}	Output Enable Time	—	2.15	—	2.50	—	2.85	—	3.00	ns
t_{DIS}	Output Disable Time	—	2.15	—	2.50	—	2.85	—	3.00	ns
t_{RSTb}	Global RESETbar Pin Delay	—	4.60	—	6.50	—	7.00	—	7.50	ns
Routing Delays										
t_{ROUTE}	Delay through SRP	—	2.80	—	4.20	—	5.65	—	6.90	ns
t_{PTSA}	Product Term Sharing Array Delay	—	0.40	—	1.85	—	2.35	—	2.50	ns
t_{PDB}	5-PT Bypass Propagation Delay	—	0.40	—	0.85	—	1.35	—	1.80	ns
t_{PDi}	Macrocell Propagation Delay	—	1.00	—	0.50	—	0.50	—	0.80	ns
t_{INREG}	Input Buffer to Macrocell Register Delay	—	3.00	—	3.05	—	3.50	—	4.40	ns
t_{FBK}	Internal Feedback Delay	—	0.00	—	0.00	—	0.00	—	0.00	ns
t_{GCLK}	Global Clock Tree Delay	—	0.85	—	0.70	—	0.55	—	0.65	ns
t_{PLL_DELAY}	Programmable PLL Delay Increment	—	0.50	—	0.50	—	0.50	—	0.50	ns
$t_{PLL_SEC_DELAY}$	Additional Delay When Using Secondary PLL Output	—	0.60	—	0.60	—	0.60	—	0.60	ns
t_{GRP}	Global Routing Pool Delay	—	1.50	—	2.25	—	3.00	—	4.00	ns
Register/Latch Delays										
t_S	D-Register Setup Time	0.65	—	0.65	—	1.05	—	1.25	—	ns
t_{S_PT}	D-Register Setup Time with PT Clock	0.65	—	0.65	—	1.05	—	1.25	—	ns
t_H	D-Register Hold Time	0.00	—	0.00	—	0.00	—	0.00	—	ns
t_{ST}	T-Register Setup Time	1.15	—	1.15	—	1.55	—	1.75	—	ns
t_{ST_PT}	T-Register Setup Time with PT Clock	1.15	—	1.15	—	1.55	—	1.75	—	ns
t_{HT}	T-Register Hold Time	0.00	—	0.00	—	0.00	—	0.00	—	ns
t_{COi}	Register Clock to Output/Feedback MUX Time	—	1.75	—	1.85	—	2.45	—	3.05	ns
t_{CES}	Clock Enable Setup Time	2.60	—	3.90	—	5.05	—	5.95	—	ns
t_{CEH}	Clock Enable Hold Time	0.60	—	0.90	—	1.20	—	1.45	—	ns
t_{SL}	Latch Setup Time	2.80	—	4.20	—	5.50	—	6.60	—	ns
t_{SL_PT}	Latch Setup Time with PT Clock	2.80	—	4.20	—	5.50	—	6.60	—	ns
t_{HL}	Latch Hold Time	0.00	—	0.00	—	0.00	—	0.00	—	ns
t_{GOi}	Latch Gate to Output/Feedback MUX Time	—	1.75	—	2.50	—	3.50	—	4.50	ns
t_{PDLi}	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	2.40	—	3.50	—	4.00	—	4.50	ns
t_{SRi}	Asynchronous Reset or Set to Output/Feedback MUX Delay	—	0.75	—	1.00	—	1.25	—	1.50	ns
t_{SRR}	Asynchronous Reset or Set Recovery Delay	—	1.00	—	1.50	—	2.00	—	2.50	ns
Control Delays										
t_{BCLK}	GLB PT Clock Delay	—	3.10	—	4.65	—	6.00	—	7.00	ns
t_{PTCLK}	Macrocell PT Clock Delay	—	3.00	—	4.50	—	6.00	—	7.00	ns

ispMACH 5768VG Timing Adders

Adder Type	Base Parameter	Description	-5		-75		-10		-12		Units
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{BLA}	t _{ROUTE}	GLB Loading Adder	—	0.0	—	0.0	—	0.0	—	0.0	ns
t _{EXP}	t _{PTSA}	PT Expander Adder	—	1.5	—	2.0	—	2.5	—	2.5	ns
t _{LP}	t _{ROUTE}	Low Power Adder	—	1.5	—	1.5	—	1.5	—	1.5	ns
t_{IOI} Input Adders											
LVC MOS18_in	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using LVC MOS1.8 standard	—	0.90	—	0.90	—	0.90	—	0.90	ns
LVC MOS25_in	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using LVC MOS2.5 standard	—	0.15	—	0.15	—	0.15	—	0.15	ns
LVC MOS33_in	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using LVC MOS3.3 standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVTTL	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using LVTTL standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
PCI_in	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using PCI standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
PCI_X_in	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using PCI_X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
AGP_1X_in	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using AGP-1X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
SSTL3_I_in	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using SSTL3_I standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
SSTL3_II_in	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using SSTL3_II standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
SSTL2_I_in	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using SSTL2_I standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
SSTL2_II_in	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using SSTL2_II standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
CTT33_in	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using CTT3.3 standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
CTT25_in	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using CTT2.5 standard	—	0.15	—	0.15	—	0.15	—	0.15	ns
HSTL_I_in	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using HSTL_I standard	—	1.25	—	1.25	—	1.25	—	1.25	ns
HSTL_III_in	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using HSTL_III standard	—	1.25	—	1.25	—	1.25	—	1.25	ns
GTL+_in	t _{IN} , t _{GCLK_IN} , t _{RSTb} , t _{GOE}	Using GTL+ standard	—	1.50	—	1.50	—	1.50	—	1.50	ns
LVDS_in	t _{GCLK_IN}	Using LVDS standard	—	1.70	—	1.70	—	1.70	—	1.70	ns
LVPECL_in	t _{GCLK_IN}	Using LVPECL standard	—	2.10	—	2.10	—	2.10	—	2.10	ns
t_{IOO} Output Adders											
LVC MOS18_4mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V & 4mA Buffer	—	3.00	—	3.00	—	3.00	—	3.00	ns
LVC MOS18_5mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V & 5.33mA Buffer	—	2.50	—	2.50	—	2.50	—	2.50	ns
LVC MOS18_8mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V & 8mA Buffer	—	1.85	—	1.85	—	1.85	—	1.85	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

Timing v.1.20

ispMACH 5768VG Timing Adders (Continued)

Adder Type	Base Parameter	Description	-5		-75		-10		-12		Units
			Min	Max	Min	Max	Min	Max	Min	Max	
LVC MOS18_12mA_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 1.8V & 12mA Buffer	—	1.35	—	1.35	—	1.35	—	1.35	ns
LVC MOS25_4mA_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 2.5V & 4mA Buffer	—	1.50	—	1.50	—	1.50	—	1.50	ns
LVC MOS25_5mA_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 2.5V & 5.33mA Buffer	—	1.25	—	1.25	—	1.25	—	1.25	ns
LVC MOS25_8mA_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 2.5V & 8mA Buffer	—	0.70	—	0.70	—	0.70	—	0.70	ns
LVC MOS25_12mA_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 2.5V & 12mA Buffer	—	0.50	—	0.50	—	0.50	—	0.50	ns
LVC MOS25_16mA_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 2.5V & 16mA Buffer	—	0.25	—	0.25	—	0.25	—	0.25	ns
LVC MOS33_4mA_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 3.3V & 4mA Buffer	—	1.50	—	1.50	—	1.50	—	1.50	ns
LVC MOS33_5mA_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 3.3V & 5.33mA Buffer	—	1.25	—	1.25	—	1.25	—	1.25	ns
LVC MOS33_8mA_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 3.3V & 8mA Buffer	—	0.40	—	0.40	—	0.40	—	0.40	ns
LVC MOS33_12mA_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 3.3V & 12mA Buffer	—	0.10	—	0.10	—	0.10	—	0.10	ns
LVC MOS33_16mA_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 3.3V & 16mA Buffer	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVC MOS33_20mA_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 3.3V & 20mA Buffer	—	0.0	—	0.0	—	0.0	—	0.0	ns
LV TTL	t_{BUF} , t_{EN} , t_{DIS}	Output configured as LV TTL Buffer	—	0.0	—	0.0	—	0.0	—	0.0	ns
Slow Slew	t_{BUF} , t_{EN}	Output configured for slow slew rate	—	1.50	—	1.50	—	1.50	—	1.50	ns
PCI_out	t_{BUF} , t_{EN} , t_{DIS}	Using PCI standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
PCI_X_out	t_{BUF} , t_{EN} , t_{DIS}	Using PCI-X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
AGP_1X_out	t_{BUF} , t_{EN} , t_{DIS}	Using AGP-1X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
SSTL3_I_out	t_{BUF} , t_{EN} , t_{DIS}	Using SSTL3_I standard	—	-0.25	—	-0.25	—	-0.25	—	-0.25	ns
SSTL3_II_out	t_{BUF} , t_{EN} , t_{DIS}	Using SSTL3_II standard	—	-0.35	—	-0.35	—	-0.35	—	-0.35	ns
SSTL2_I_out	t_{BUF} , t_{EN} , t_{DIS}	Using SSTL2_I standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
SSTL2_II_out	t_{BUF} , t_{EN} , t_{DIS}	Using SSTL2_II standard	—	-0.25	—	-0.25	—	-0.25	—	-0.25	ns
CTT33_out	t_{BUF} , t_{EN} , t_{DIS}	Using CCT3.3 standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
CTT25_out	t_{BUF} , t_{EN} , t_{DIS}	Using CCT2.5 standard	—	0.25	—	0.25	—	0.25	—	0.25	ns
HSTL_I_out	t_{BUF} , t_{EN} , t_{DIS}	Using HSTL_I standard	—	-0.30	—	-0.30	—	-0.30	—	-0.30	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

Timing v.1.20

ispMACH 51024VG Timing Adders (Continued)

Adder Type	Base Parameter	Description	-5		-75		-10		-12		Units
			Min	Max	Min	Max	Min	Max	Min	Max	
LVDS_in	t _{GCLK_IN}	Using LVDS standard	—	1.70	—	1.70	—	1.70	—	1.70	ns
LVPECL_in	t _{GCLK_IN}	Using LVPECL standard	—	2.10	—	2.10	—	2.10	—	2.10	ns
t_{IO0} Output Adders											
LVC MOS18_4mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V & 4mA Buffer	—	3.00	—	3.00	—	3.00	—	3.00	ns
LVC MOS18_5mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V & 5.33mA Buffer	—	2.50	—	2.50	—	2.50	—	2.50	ns
LVC MOS18_8mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V & 8mA Buffer	—	1.85	—	1.85	—	1.85	—	1.85	ns
LVC MOS18_12mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V & 12mA Buffer	—	1.35	—	1.35	—	1.35	—	1.35	ns
LVC MOS25_4mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 2.5V & 4mA Buffer	—	1.50	—	1.50	—	1.50	—	1.50	ns
LVC MOS25_5mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 2.5V & 5.33mA Buffer	—	1.25	—	1.25	—	1.25	—	1.25	ns
LVC MOS25_8mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 2.5V & 8mA Buffer	—	0.70	—	0.70	—	0.70	—	0.70	ns
LVC MOS25_12mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 2.5V & 12mA Buffer	—	0.50	—	0.50	—	0.50	—	0.50	ns
LVC MOS25_16mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 2.5V & 16mA Buffer	—	0.25	—	0.25	—	0.25	—	0.25	ns
LVC MOS33_4mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 3.3V & 4mA Buffer	—	1.50	—	1.50	—	1.50	—	1.50	ns
LVC MOS33_5mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 3.3V & 5.33mA Buffer	—	1.25	—	1.25	—	1.25	—	1.25	ns
LVC MOS33_8mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 3.3V & 8mA Buffer	—	0.40	—	0.40	—	0.40	—	0.40	ns
LVC MOS33_12mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 3.3V & 12mA Buffer	—	0.10	—	0.10	—	0.10	—	0.10	ns
LVC MOS33_16mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 3.3V & 16mA Buffer	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVC MOS33_20mA_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 3.3V & 20mA Buffer	—	0.0	—	0.0	—	0.0	—	0.0	ns
LV TTL	t _{BUF} , t _{EN} , t _{DIS}	Output configured as LV TTL Buffer	—	0.0	—	0.0	—	0.0	—	0.0	ns
Slow Slew	t _{BUF} , t _{EN}	Output configured for slow slew rate	—	1.50	—	1.50	—	1.50	—	1.50	ns
PCI_out	t _{BUF} , t _{EN} , t _{DIS}	Using PCI standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
PCI_X_out	t _{BUF} , t _{EN} , t _{DIS}	Using PCI-X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
AGP_1X_out	t _{BUF} , t _{EN} , t _{DIS}	Using AGP-1X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
SSTL3_I_out	t _{BUF} , t _{EN} , t _{DIS}	Using SSTL3_I standard	—	-0.25	—	-0.25	—	-0.25	—	-0.25	ns
SSTL3_II_out	t _{BUF} , t _{EN} , t _{DIS}	Using SSTL3_II standard	—	-0.35	—	-0.35	—	-0.35	—	-0.35	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

Timing v.1.10

ispMACH 51024VG Timing Adders (Continued)

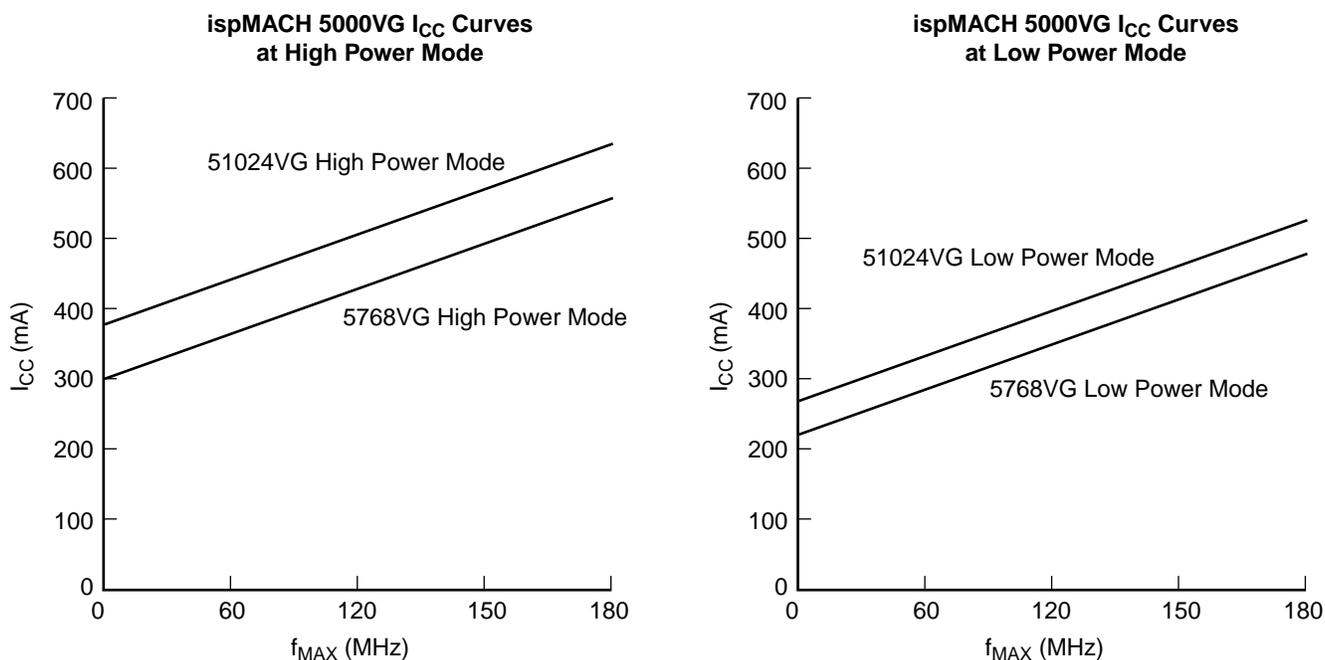
Adder Type	Base Parameter	Description	-5		-75		-10		-12		Units
			Min	Max	Min	Max	Min	Max	Min	Max	
SSTL2_I_out	t_{BUF} , t_{EN} , t_{DIS}	Using SSTL2_I standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
SSTL2_II_out	t_{BUF} , t_{EN} , t_{DIS}	Using SSTL2_II standard	—	-0.25	—	-0.25	—	-0.25	—	-0.25	ns
CTT33_out	t_{BUF} , t_{EN} , t_{DIS}	Using CCT3.3 standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
CTT25_out	t_{BUF} , t_{EN} , t_{DIS}	Using CCT2.5 standard	—	0.25	—	0.25	—	0.25	—	0.25	ns
HSTL_I_out	t_{BUF} , t_{EN} , t_{DIS}	Using HSTL_I standard	—	-0.30	—	-0.30	—	-0.30	—	-0.30	ns
HSTL_III_out	t_{BUF} , t_{EN} , t_{DIS}	Using HSTL_III standard	—	0.00	—	0.00	—	0.00	—	0.00	ns
GTL+_out	t_{BUF} , t_{EN} , t_{DIS}	Using GTL+ standard	—	0.30	—	0.30	—	0.30	—	0.30	ns

Note: Open drain timing is the same as corresponding LVCMOS timing.

Timing v.1.10

Power Consumption

ispMACH 5000VG Typical Power vs. Frequency



Note: The devices are configured with maximum number of 16-bit counters, no PLL, typical current at 3.3V, 25° C.

Power Estimation Coefficients

Device	K0	K1	K2	K3	K4	K5	K6	I_{DC} (mA)	I_{DCO} (mA)
ispMACH 5768VG	0.0014	0.0014	0.054	1.5	0.152	0.105	5.0	65	20
ispMACH 51024VG	0.0014	0.0014	0.054	1.5	0.152	0.105	5.0	80	20

Note: For further information about the use of these coefficients, refer to Technical Note TN1002, *Power Estimation in ispMACH 5000VG Devices*.

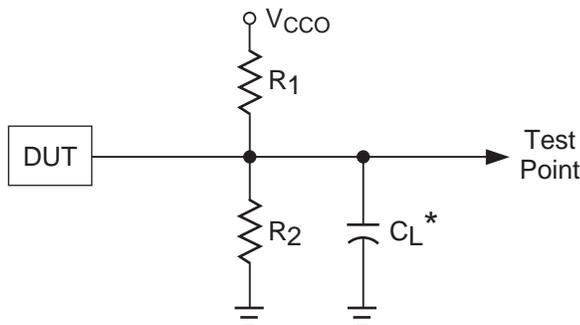
- K0 = average current per product term in high power/MHz
- K1 = average current per product term in low power/MHz
- K2 = average current per GRP line/MHz
- K3 = average current per PLL/MHz
- K4 = DC current per product terms in high power
- K5 = DC current per product terms in low power
- K6 = Static DC current per PLL
- I_{DC} = Static device current with all product terms powered off
- I_{DCO} = Static I/O bank current

I_{CC} estimates are based on typical conditions ($V_{CC} = 3.3V$, room temperature) and an assumption of one GLB load on average exists. These values are for estimates only. Since the value of I_{CC} is sensitive to operating conditions and the program in the device, the actual I_{CC} should be verified.

Switching Test Conditions

Figure 12 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 3.

Figure 12. Output Test Load, LVTTTL and LVCMOS Standards



*CL includes Test Fixture and Probe Capacitance.

0213A/ispm5kvg

Table 3. Test Fixture Required Components

Test Condition	R ₁	R ₂	C _L	Timing Ref.	V _{CCO}
Default LVCMOS 3.3 I/O (L -> H, H -> L)	110	110	35pF	1.5	3.0V
Other LVCMOS Settings, (L -> H, H -> L)	∞	∞	35pF	LVCMOS 3.3 = 1.5V	LVCMOS 3.3 = 3.0V
				LVCMOS 2.5 = V _{CCO} /2	LVCMOS 2.5 = 2.3V
				LVCMOS 1.8 = V _{CCO} /2	LVCMOS 1.8 = 1.65V
Default LVCMOS 3.3 I/O (Z -> H)	∞	110	35pF	1.5V	3.0V
Default LVCMOS 3.3 I/O (Z -> L)	110	∞	35pF	1.5V	3.0V
Default LVCMOS 3.3 I/O (H -> Z)	∞	110	5pF	V _{OH} - 0.3	3.0V
Default LVCMOS 3.3 I/O (L -> Z)	110	∞	5pF	V _{OL} + 0.3	3.0V

Output test conditions for all other interfaces are determined by the respective standards. For further details, please refer to the following technical note:

- *ispMACH 5000VG sysIO Design and Usage Guidelines (TN1000)*

ispMACH 5768VG Logic Signal Connections (Continued)

Bank No.	Signal	256 fpBGA	484 fpBGA
0	1A-30	NC	K5
0	GNDIO0	GND	GND
0	1B-30/CLK_OUT0	G6	N1
0	1B-28	NC	M2
0	1B-26	NC	P1
0	1B-24	NC	L4
0	1B-22	F5	N2
0	1B-20	E2	M3
0	1B-18	E1	L5
0	1B-16	F4	R1
0	1B-14	F3	P2
0	1B-12	F2	N3
0	GNDIO0	GND	GND
0	1B-10	G5	M6
0	1B-8	G4	M5
0	1B-6/PLL_RST0	F1	M4
0	1B-4/PLL_FBK0	G2	N4
0	1B-2	G1	N6
0	1B-0	H5	N5
1	2B-0	K1	R5
1	2B-2	K2	T2
1	2B-4	L1	T5
1	2B-6	J5	T3
1	2B-8	L2	U1
1	2B-10	K4	U4
1	GNDIO1	GND	GND
1	2B-12	M1	V1
1	2B-14	L3	U3
1	2B-16	L4	V5
1	2B-18	K5	V2
1	2B-20	M2	W1
1	2B-22	N1	V3
1	2B-24	NC	W2
1	2B-26	K6	Y1
1	2B-28	L5	Y2
1	2B-30	N2	W3
1	2A-30	L6	AA3
1	2A-28	L7	W4
1	GNDIO1	GND	GND
1	2A-26	P1	W5
1	2A-24	P2	Y4
1	2A-22	N3	T6
1	2A-20	R4	Y5

Bank No.	Signal	256 fpBGA	484 fpBGA
1	2A-18	NC	U6
1	2A-16	R1	AA4
1	2A-14	NC	NC
1	2A-12	NC	NC
1	GNDIO1	GND	GND
1	2A-10	NC	NC
1	2A-8	NC	NC
1	2A-6	T1	W6
1	2A-4	T2	V4
1	2A-2	R2	U7
1	2A-0	T3	AB2
1	2D-0	R3	V7
1	2D-2	P4	AA5
1	GNDIO1	GND	GND
1	2D-4	T4	AB3
1	2D-6	N4	Y6
1	2D-8	M4	AB4
1	2D-10	N5	Y7
1	2D-12	R5	AB5
1	2D-14	T5	V8
1	2D-16	NC	AA7
1	2D-18	NC	Y8
1	2D-20	NC	AB6
1	2D-22	T6	W8
1	2D-24	R6	AA8
1	2D-26	P6	Y10
1	GNDIO1	GND	GND
1	2D-28	M5	U8
1	2D-30	T7	AB7
1	2C-0	T8	U9
1	2C-2	R8	AA9
1	2C-4	M6	W9
1	2C-6	N6	AB8
1	2C-8	R7	U10
1	2C-10	T9	AB9
1	2C-12	T10	V11
1	2C-14/VREF1	M7	AA10
1	2C-16	N7	V10
1	2C-18	P8	AB10
1	GNDIO1	GND	GND
1	2C-20	R9	W10
1	2C-22	N8	W11
1	2C-24	M8	U11

ispMACH 5768VG Logic Signal Connections (Continued)

Bank No.	Signal	256 fpBGA	484 fpBGA
3	5C-20	C9	A13
3	5C-22	E9	B12
3	5C-24	D9	C13
3	5C-26	B8	A12
3	5C-28	A6	C12
3	5C-30	B7	A11
—	GCLK0	H4	P6
—	GCLK1	J4	R6
—	GCLK2	H14	P17
—	GCLK3	H13	P19
—	GOE0	J15	R18
—	GOE1	H15	R17
—	RESETB	J14	R19
—	TCK	J3	R3
—	TDI	H3	R2
—	TDO	J2	R4
—	TMS	H2	T1
—	TOE	J13	T18

ispMACH 51024VG Logic Signal Connections

Bank No.	Signal	484 fpBGA	676 fpBGA
0	0C-30	D11	A13
0	0C-28	B11	B13
0	0C-26	E12	A12
0	0C-24	C11	B12
0	0C-22	F12	C12
0	0C-20	B10	A11
0	GNDIO0	GND	GND
0	0C-18	A10	B11
0	0C-16	D10	A10
0	0C-14/VREF0	A9	C11
0	0C-12	E11	E12
0	0C-10	B9	B10
0	0C-8	F11	D11
0	0C-6	A8	A9
0	0C-4	C10	C10
0	0C-2	A7	B9
0	0C-0	E10	A8
0	0D-30	B8	C9
0	0D-28	C8	B8
0	GNDIO0	GND	GND
0	0D-26	F10	E10
0	0D-24	A6	A7
0	0D-22	F9	D9
0	0D-20	C7	C8
0	0D-18	D9	B7
0	0D-16	B7	A6
0	0D-14	E8	C7
0	0D-12	A5	B6
0	0D-10	F8	A5
0	0D-8	C6	C6
0	0D-6	D8	D7
0	0D-4	A3	E8
0	GNDIO0	GND	GND
0	0D-2	A2	B5
0	0D-0	A4	A4
0	0A-0	F7	A3
0	0A-2	C5	B4
0	0A-4	F6	C5
0	0A-6	B3	F8
0	0A-8	NC	A2
0	0A-10	NC	B3
0	GNDIO0	GND	GND
0	0A-12	NC	C4

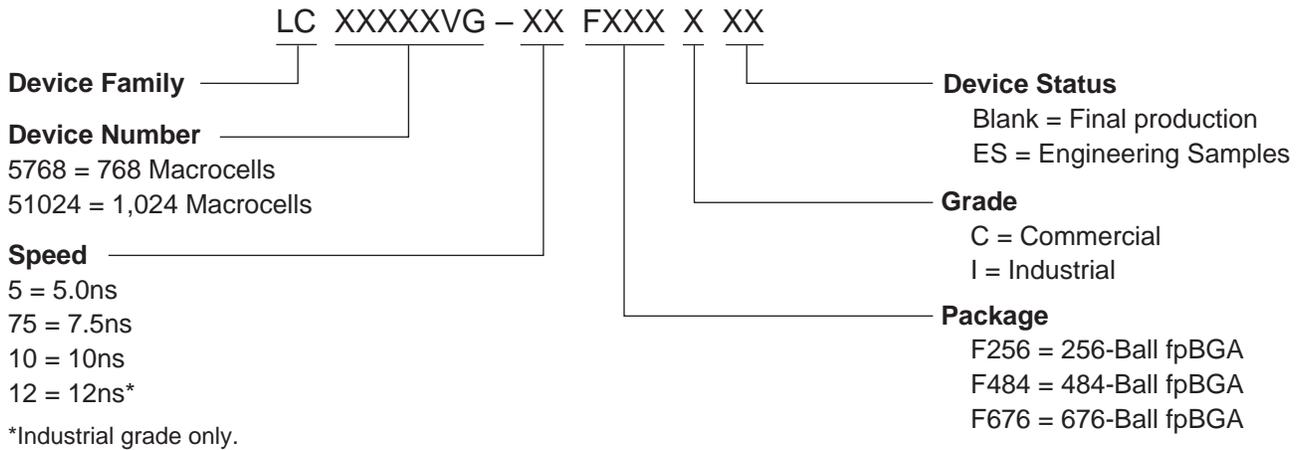
Bank No.	Signal	484 fpBGA	676 fpBGA
0	0A-14	NC	D5
0	0A-16	B4	E6
0	0A-18	D5	D4
0	0A-20	B1	B1
0	0A-22	D6	C2
0	0A-24	C4	F6
0	0A-26	E4	D3
0	GNDIO0	GND	GND
0	0A-28	C2	E4
0	0A-30	C1	F5
0	0B-30	D1	C1
0	0B-28	D2	D2
0	0B-26	D3	E3
0	0B-24	E1	D1
0	0B-22	E3	E2
0	0B-20	F4	H6
0	0B-18	F1	F3
0	0B-16	F3	E1
0	0B-14	G6	G4
0	0B-12	G1	F2
0	GNDIO0	GND	GND
0	0B-10	G2	H5
0	0B-8	H1	G3
0	0B-6	G3	F1
0	0B-4	H2	G2
0	0B-2	H5	H3
0	0B-0	H6	G1
0	1A-0	J1	H2
0	1A-2	K1	J4
0	1A-4	H3	H1
0	1A-6	J2	J3
0	1A-8	H4	K5
0	1A-10	K2	J2
0	GNDIO0	GND	GND
0	1A-12	J6	J1
0	1A-14	L1	K3
0	1A-16	K3	K2
0	1A-18	J4	K1
0	1A-20	L2	L4
0	1A-22	M1	L3
0	1A-24	K6	L2
0	1A-26	K4	M5
0	1A-28	L3	L1

ispMACH 51024VG Logic Signal Connections (Continued)

Bank No.	Signal	484 fpBGA	676 fpBGA
0	1A-30	K5	M3
0	GNDIO0	GND	GND
0	1B-30/CLK_OUT0	N1	M2
0	1B-28	M2	M1
0	1B-26	P1	N6
0	1B-24	L4	N5
0	1B-22	N2	N4
0	1B-20	M3	N3
0	1B-18	L5	N2
0	1B-16	R1	N1
0	1B-14	P2	P6
0	1B-12	N3	P4
0	GNDIO0	GND	GND
0	1B-10	M6	P3
0	1B-8	M5	P2
0	1B-6/PLL_RST0	M4	P1
0	1B-4/PLL_FBK0	N4	R4
0	1B-2	N6	R3
0	1B-0	N5	R2
1	2B-0	NC	R1
1	2B-2	NC	T1
1	2B-4	NC	T3
1	2B-6	NC	T2
1	2B-8	NC	U1
1	2B-10	NC	U2
1	GNDIO1	GND	GND
1	2B-12	NC	U3
1	2B-14	NC	U4
1	2B-16	NC	V1
1	2B-18	NC	V2
1	2B-20	NC	V3
1	2B-22	NC	V4
1	2B-24	NC	W1
1	2B-26	NC	V6
1	2B-28	NC	W2
1	2B-30	NC	W3
1	GNDIO1	GND	GND
1	2A-30	NC	Y1
1	2A-28	NC	W5
1	2A-26	NC	Y2
1	2A-24	NC	Y3
1	2A-22	NC	AA1
1	2A-20	NC	Y4

Bank No.	Signal	484 fpBGA	676 fpBGA
1	2A-18	NC	AA2
1	2A-16	NC	AA3
1	2A-14	NC	AB1
1	2A-12	NC	AB2
1	GNDIO1	GND	GND
1	2A-10	NC	AA5
1	2A-8	NC	AB3
1	2A-6	NC	AC1
1	2A-4	NC	AB4
1	2A-2	NC	AC2
1	2A-0	NC	AD1
1	3B-0	R5	AC3
1	3B-2	T2	AD2
1	3B-4	T5	AE1
1	3B-6	T3	AD3
1	3B-8	U1	AE2
1	3B-10	U4	AC5
1	GNDIO1	GND	GND
1	3B-12	V1	AF1
1	3B-14	U3	AD4
1	3B-16	V5	AE3
1	3B-18	V2	AC6
1	3B-20	W1	AF2
1	3B-22	V3	AG1
1	3B-24	W2	AF3
1	3B-26	Y1	AG2
1	3B-28	Y2	AH1
1	3B-30	W3	AE5
1	3A-30	AA3	AF4
1	3A-28	W4	AG3
1	GNDIO1	GND	GND
1	3A-26	W5	AE6
1	3A-24	Y4	AH2
1	3A-22	T6	AJ1
1	3A-20	Y5	AG4
1	3A-18	U6	AF6
1	3A-16	AA4	AG5
1	3A-14	NC	AH4
1	3A-12	NC	AJ3
1	GNDIO1	GND	GND
1	3A-10	NC	AK2
1	3A-8	NC	AE8
1	3A-6	W6	AH5

Part Number Description



0212/isp5vg

Ordering Information

Commercial

Part Number	Package	Pin Count	Macrocells	Tpd	Voltage
LC51024VG-5F484C	fpBGA	484	1024	5	3.3
LC51024VG-75F484C	fpBGA	484	1024	7.5	3.3
LC51024VG-10F484C	fpBGA	484	1024	10	3.3
LC51024VG-5F676C	fpBGA	676	1024	5	3.3
LC51024VG-75F676C	fpBGA	676	1024	7.5	3.3
LC51024VG-10F676C	fpBGA	676	1024	10	3.3
LC5768VG-5F256C	fpBGA	256	768	5	3.3
LC5768VG-75F256C	fpBGA	256	768	7.5	3.3
LC5768VG-10F256C	fpBGA	256	768	10	3.3
LC5768VG-5F484C	fpBGA	484	768	5	3.3
LC5768VG-75F484C	fpBGA	484	768	7.5	3.3
LC5768VG-10F484C	fpBGA	484	768	10	3.3

Note: the ispMACH 5000VG family is dual-marked with both Commercial and Industrial grades. The Commercial speed grade is one speed grade faster (i.e. LC51024VG-75F484C) than the Industrial speed grade (i.e. LC51024VG-10F484I).

Industrial

Part Number	Package	Pin Count	Macrocells	Tpd	Voltage
LC51024VG-75F484I	fpBGA	484	1024	7.5	3.3
LC51024VG-10F484I	fpBGA	484	1024	10	3.3
LC51024VG-12F484I	fpBGA	484	1024	12	3.3
LC51024VG-75F676I	fpBGA	676	1024	7.5	3.3
LC51024VG-10F676I	fpBGA	676	1024	10	3.3
LC51024VG-12F676I	fpBGA	676	1024	12	3.3
LC5768VG-75F256I	fpBGA	256	768	7.5	3.3
LC5768VG-10F256I	fpBGA	256	768	10	3.3
LC5768VG-12F256I	fpBGA	256	768	12	3.3
LC5768VG-75F484I	fpBGA	484	768	7.5	3.3
LC5768VG-10F484I	fpBGA	484	768	10	3.3
LC5768VG-12F484I	fpBGA	484	768	12	3.3

Note: the ispMACH 5000VG family is dual-marked with both Commercial and Industrial grades. The Commercial speed grade is one speed grade faster (i.e. LC51024VG-75F484C) than the Industrial speed grade (i.e. LC51024VG-10F484I).

For Further Information

In addition to this data sheet, the following technical notes may be helpful when designing with the ispMACH 5000VG family:

- *ispMACH 5000VG sysIO Design and Usage Guidelines (TN1000)*
- *ispMACH 5000VG Timing Model Design and Usage Guidelines (TN1001)*
- *Power Estimation in ispMACH 5000VG Devices (TN1002)*
- *ispMACH 5000VG PLL Usage Guidelines (TN1003)*